These assemblies are ESD sensitive, ESD precautions shall be observed.
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated.
Assembly variant: 001

Board #: TIDA-01160
Rev: E1
Sun Rev: Not In VersionControl

Layer name = M5 Assembly Top
Tid #: TIDA-01160

Plot name = Top Assembly Drawing
Generated: 5/2/2017 1:58:46 PM
Texas Instruments
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01160</th>
<th>REV: E1</th>
<th>SVN REV: Not In VersionControl</th>
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<tr>
<td>LAYER NAME = M6 Assembly Bottom</td>
<td>TID #: TIDA-01160</td>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 5/2/2017 1:58:47 PM</td>
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<td>TEXAS INSTRUMENTS</td>
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